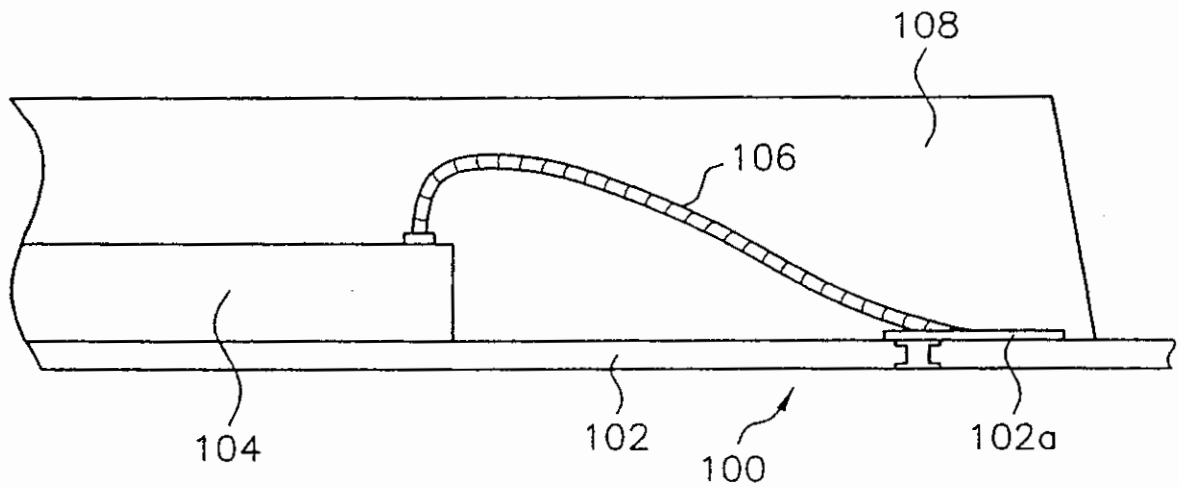


FIG. 1
(Prior Art)

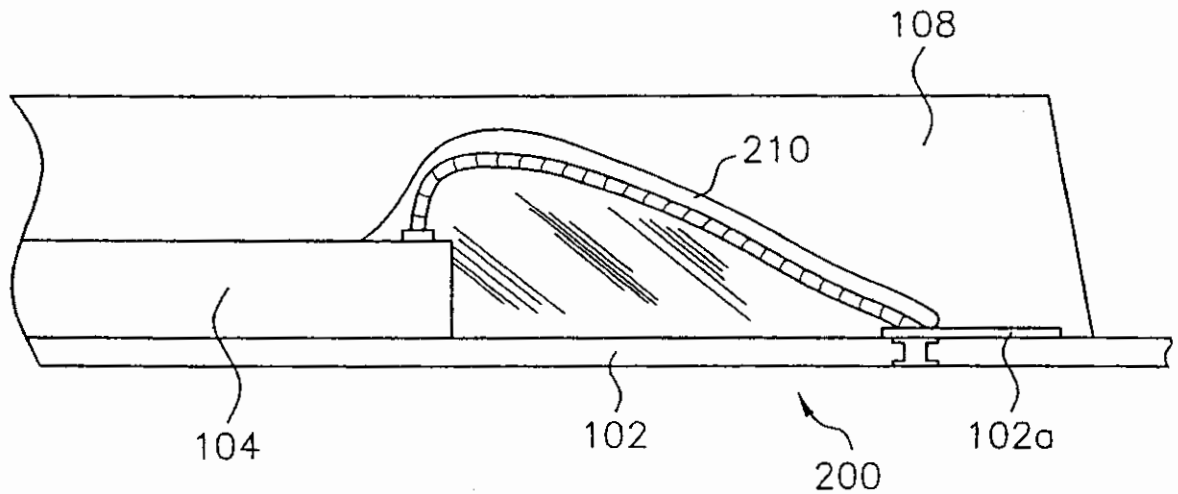


FIG. 2
(Prior Art)

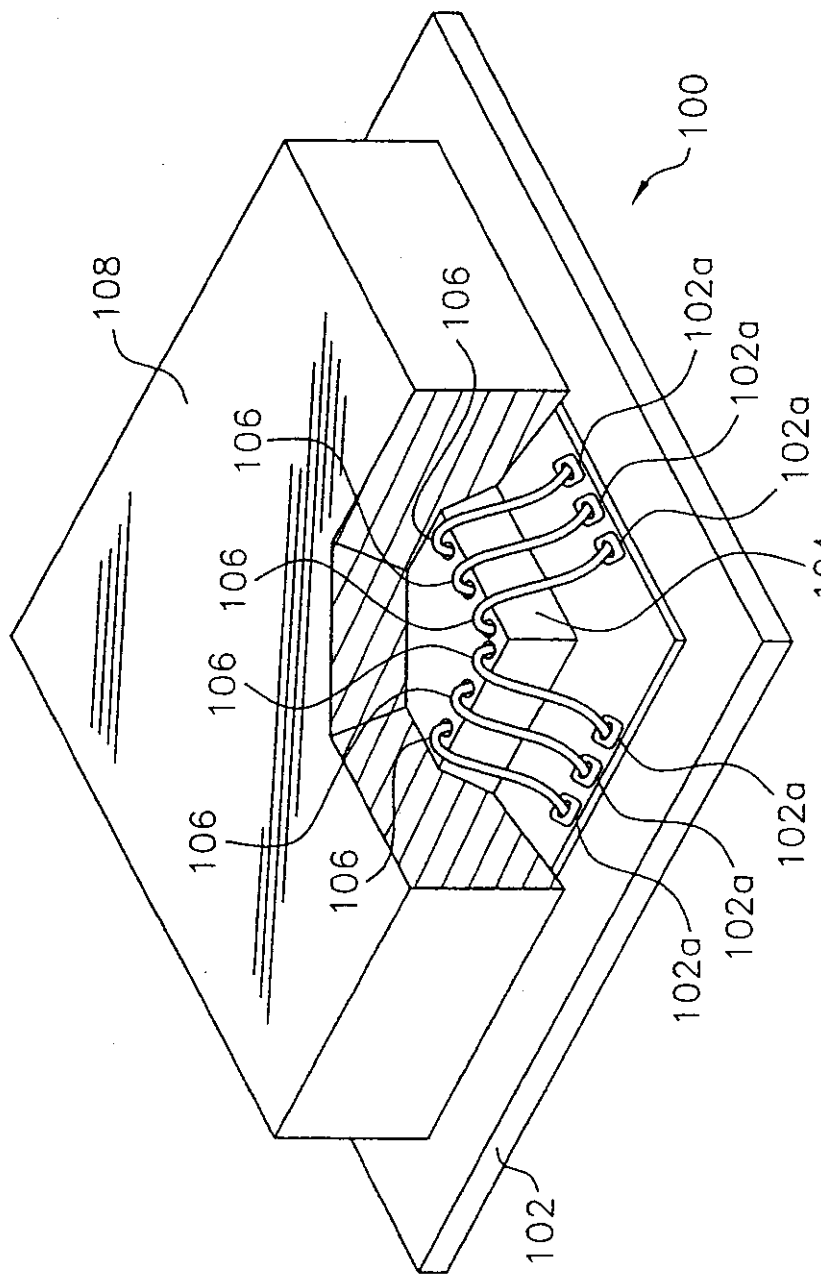


FIG. 3
(Prior Art)

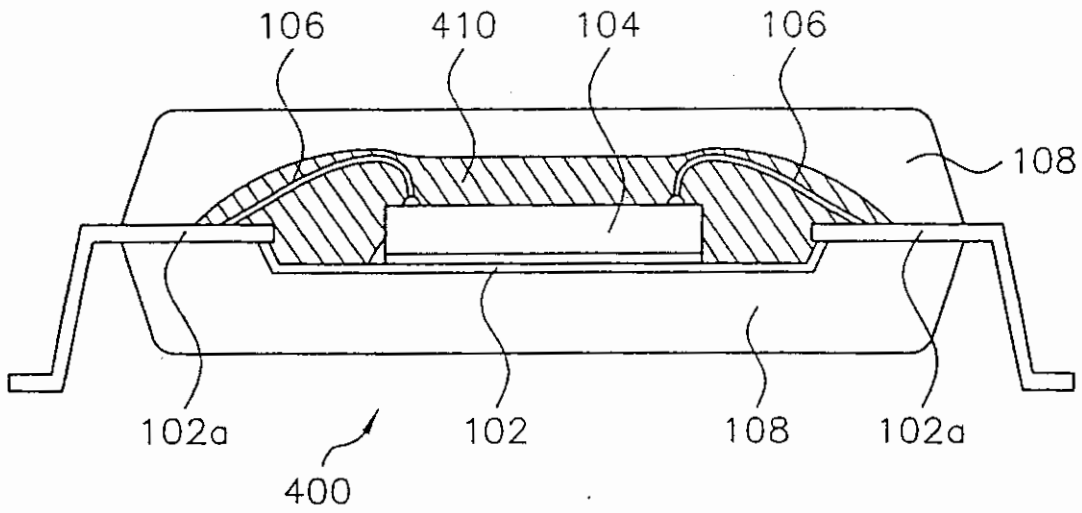


FIG. 4
(Prior Art)

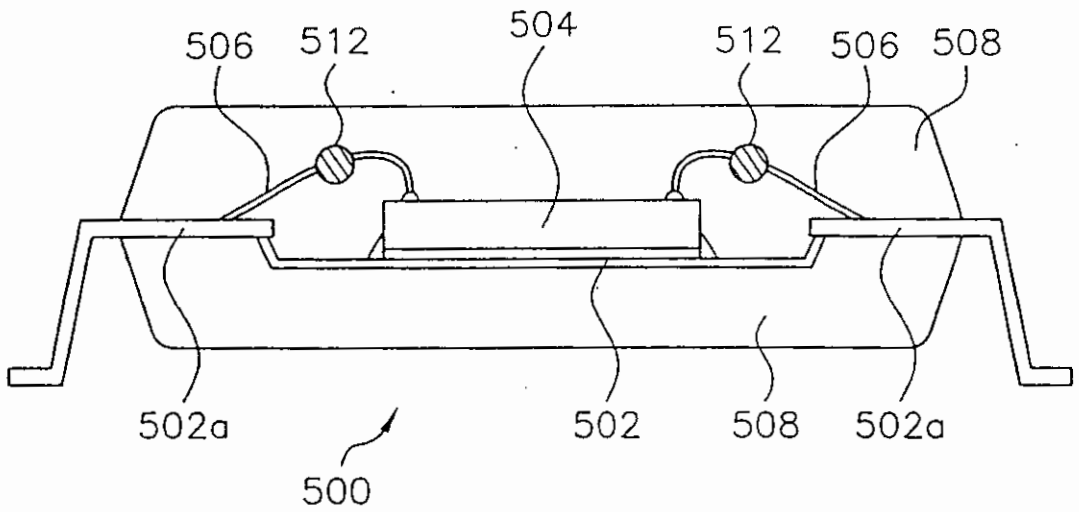


FIG. 5

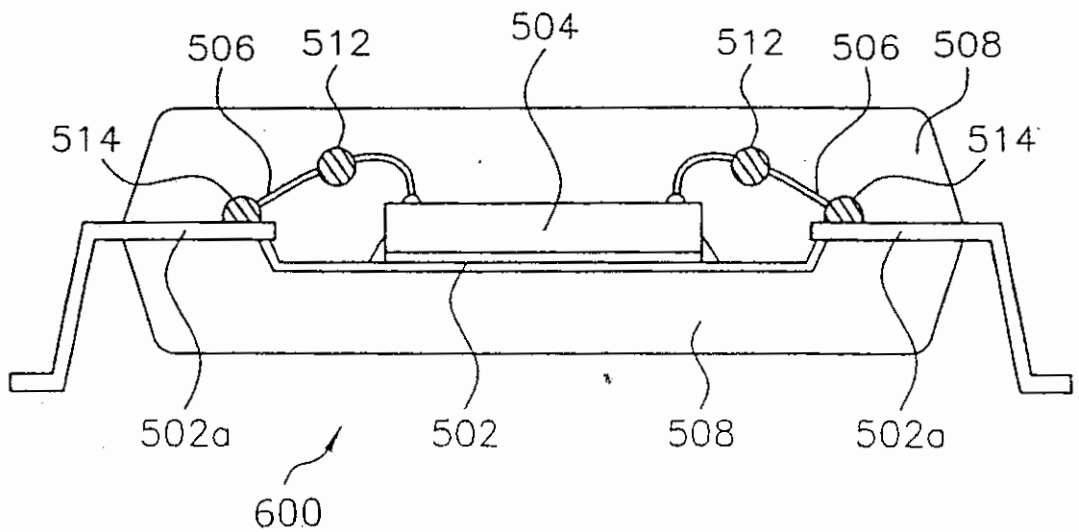


FIG. 6

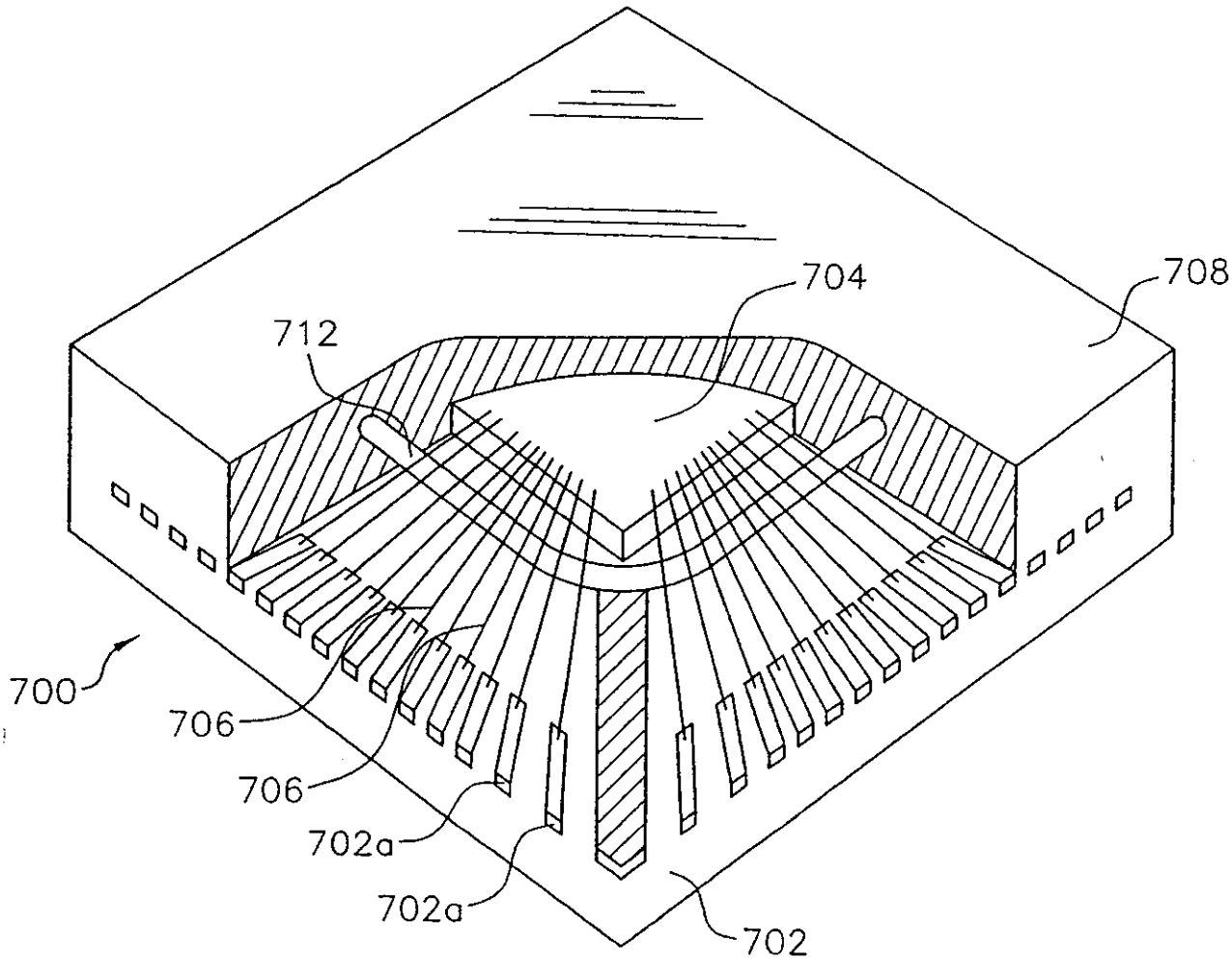


FIG. 7

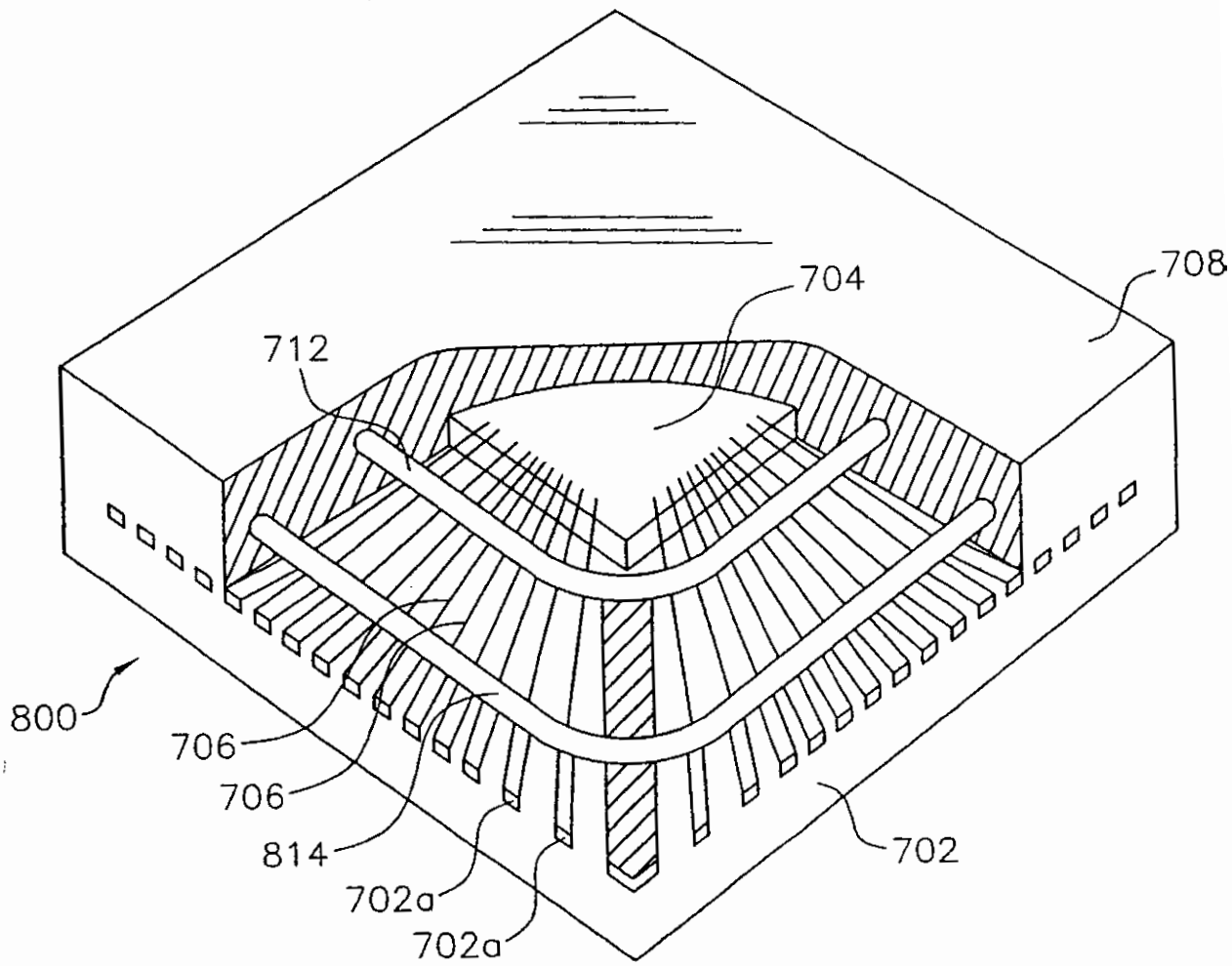


FIG. 8

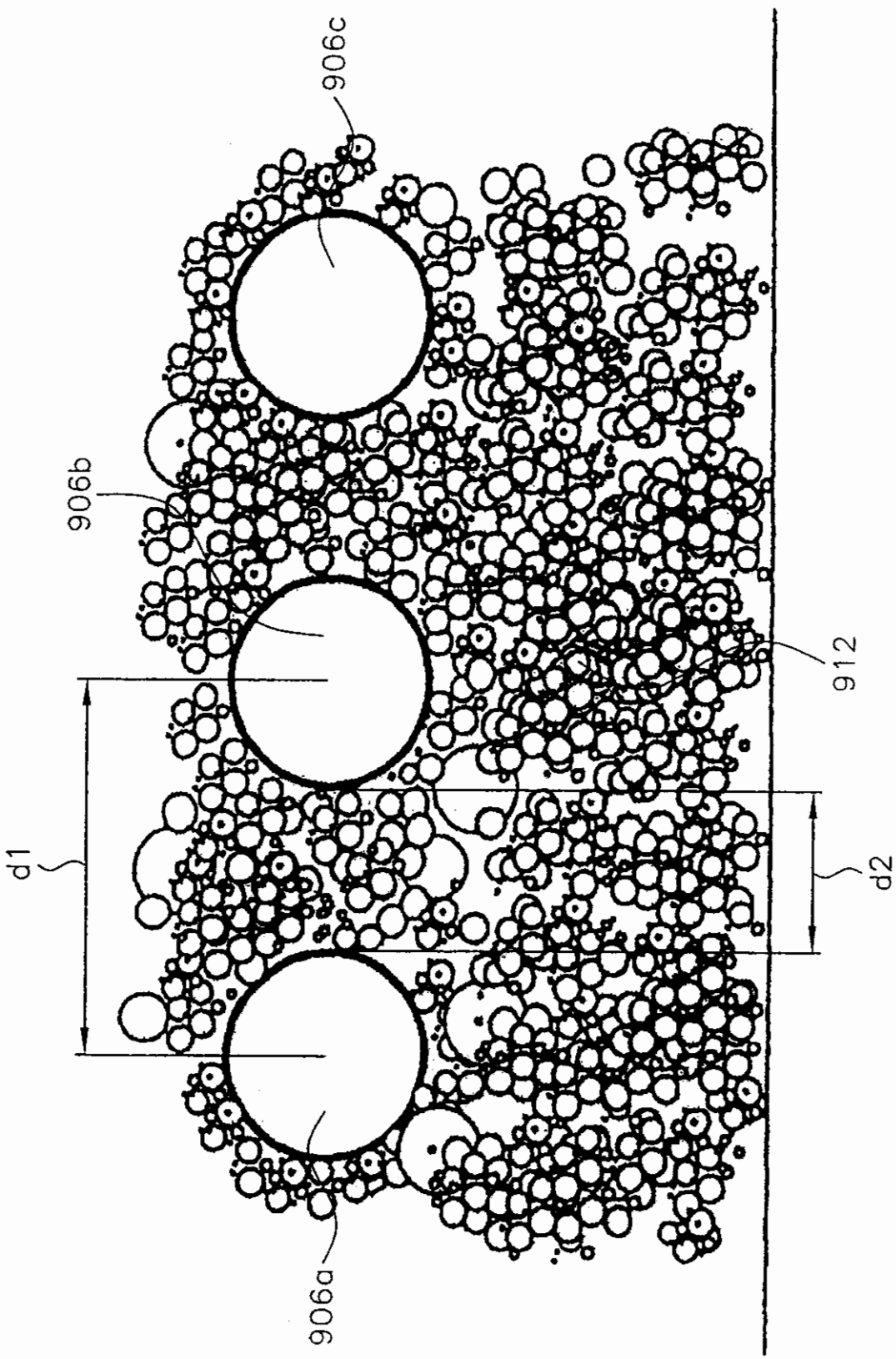


FIG. 9

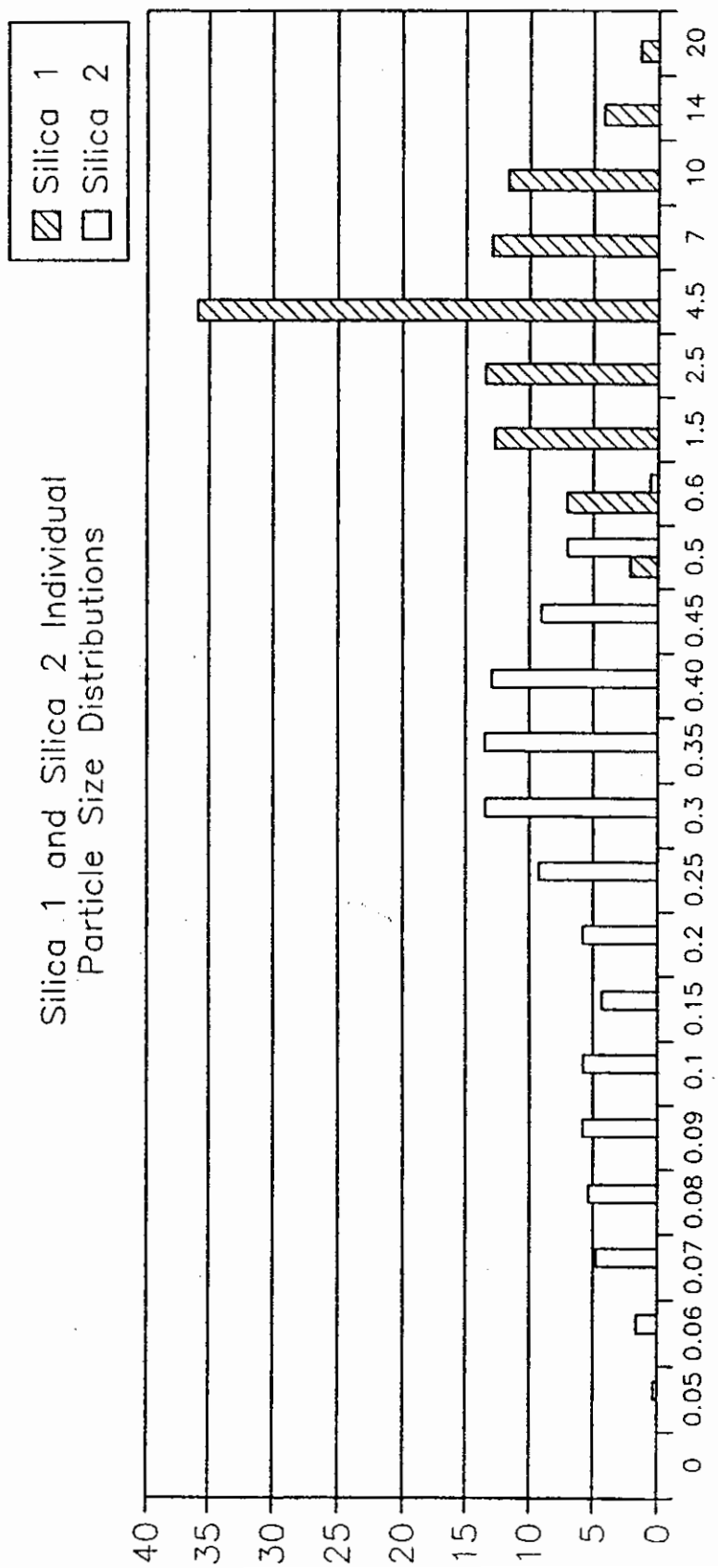

Silica 1 and Silica 2 Individual
Particle Size Distributions
Silica 1
Silica 2
40
35
30
25
20
15
10
5
0
0 0.05 0.06 0.07 0.08 0.09 0.1 0.15 0.2 0.25 0.3 0.35 0.40 0.45 0.5 0.6 1.5 2.5 4.5 7 10 14 20
Size range (µm)

FIG. 10

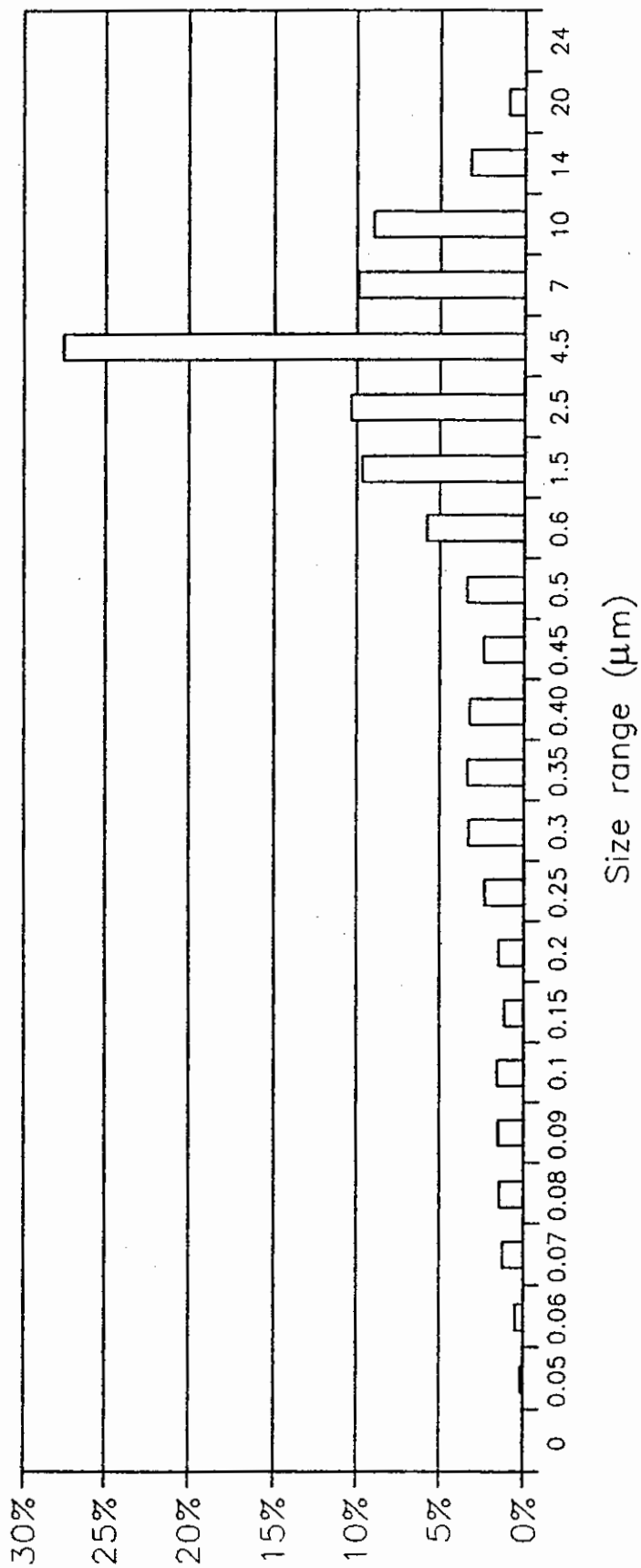

Silica (SiO_2) Particle Size Distribution
30%
25%
20%
15%
10%
5%
0%
0 0.05 0.06 0.07 0.08 0.09 0.1 0.15 0.2 0.25 0.3 0.35 0.40 0.45 0.5 0.6 1.5 2.5 4.5 7 10 14 20 24
Size range (µm)

FIG. 11

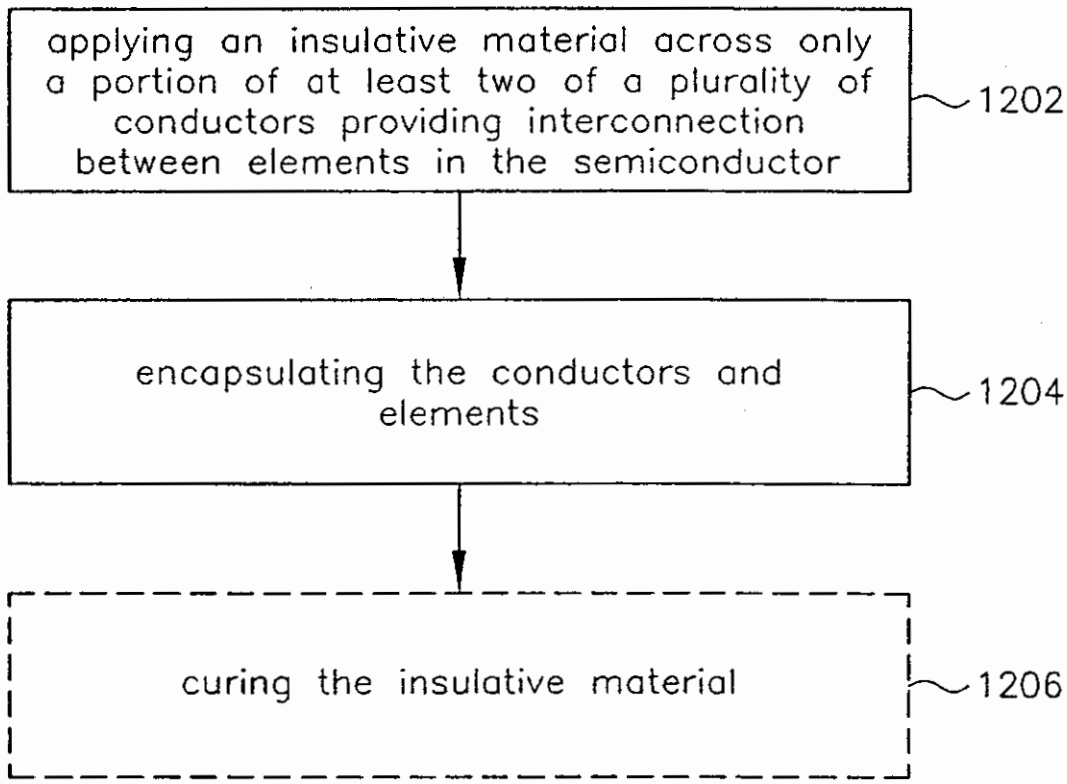

applying an insulative material across only a portion of at least two of a plurality of conductors providing interconnection between elements in the semiconductor
1202
encapsulating the conductors and elements
1204
curing the insulative material
1206

FIG. 12

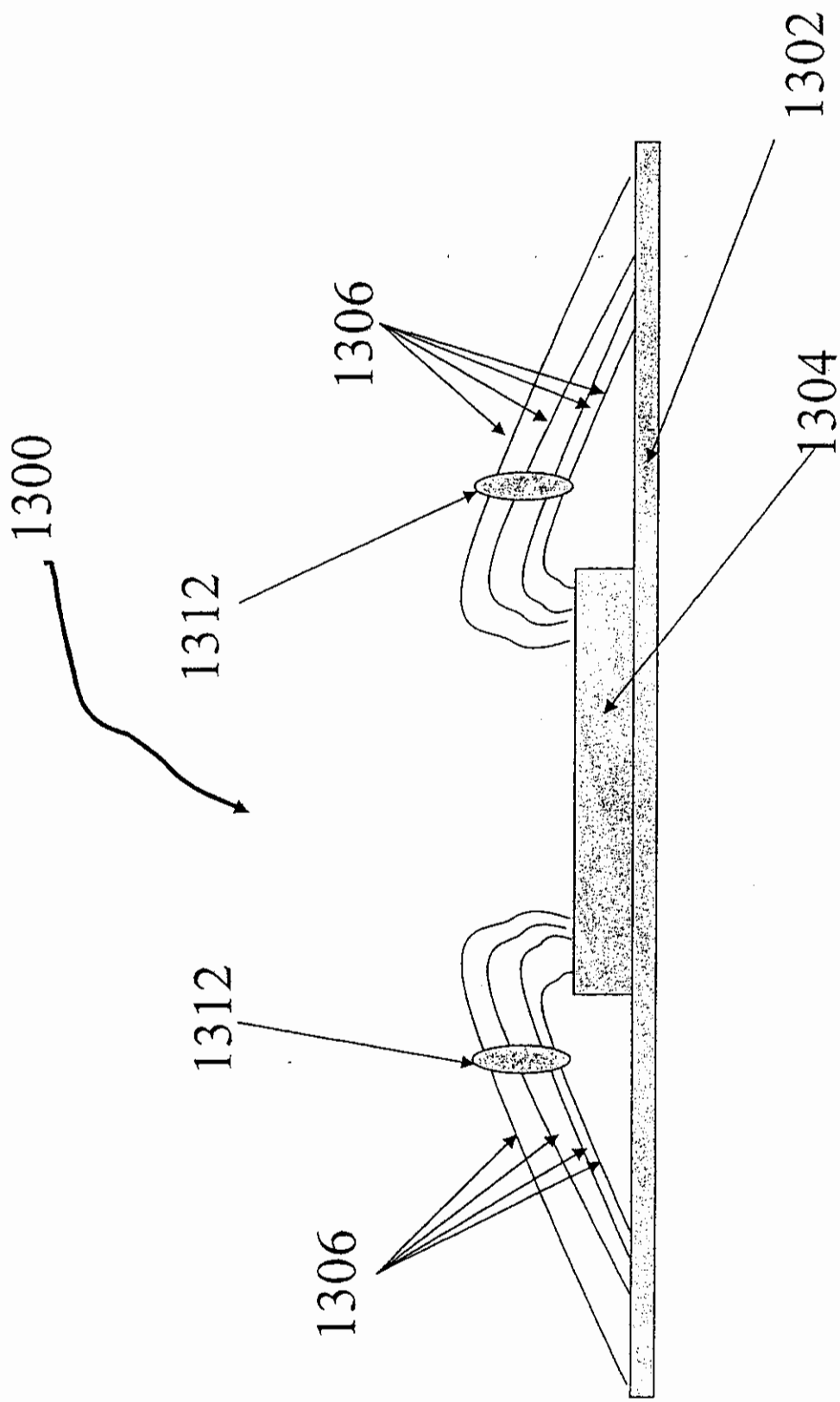


Fig. 13A

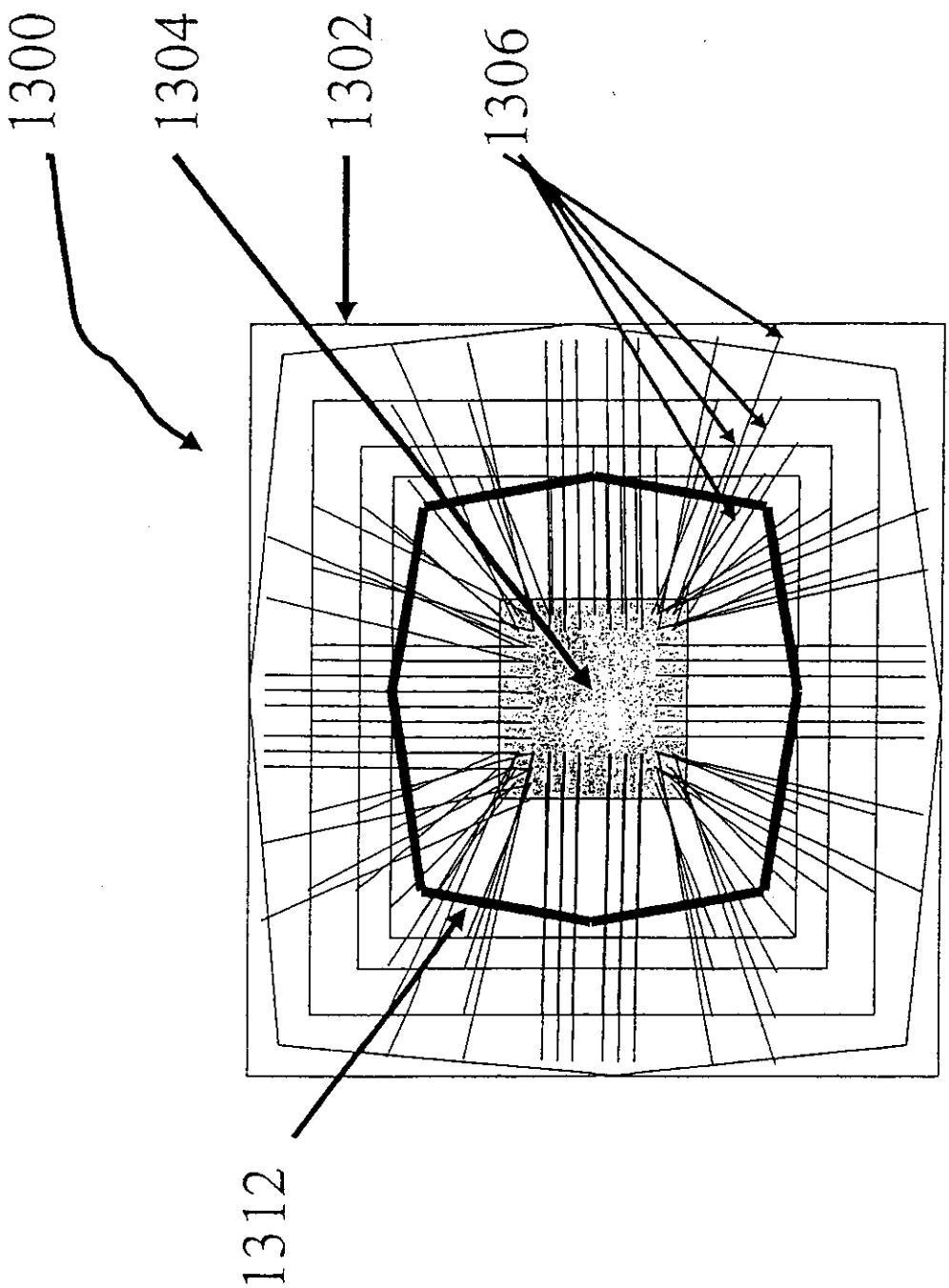


Fig.13B

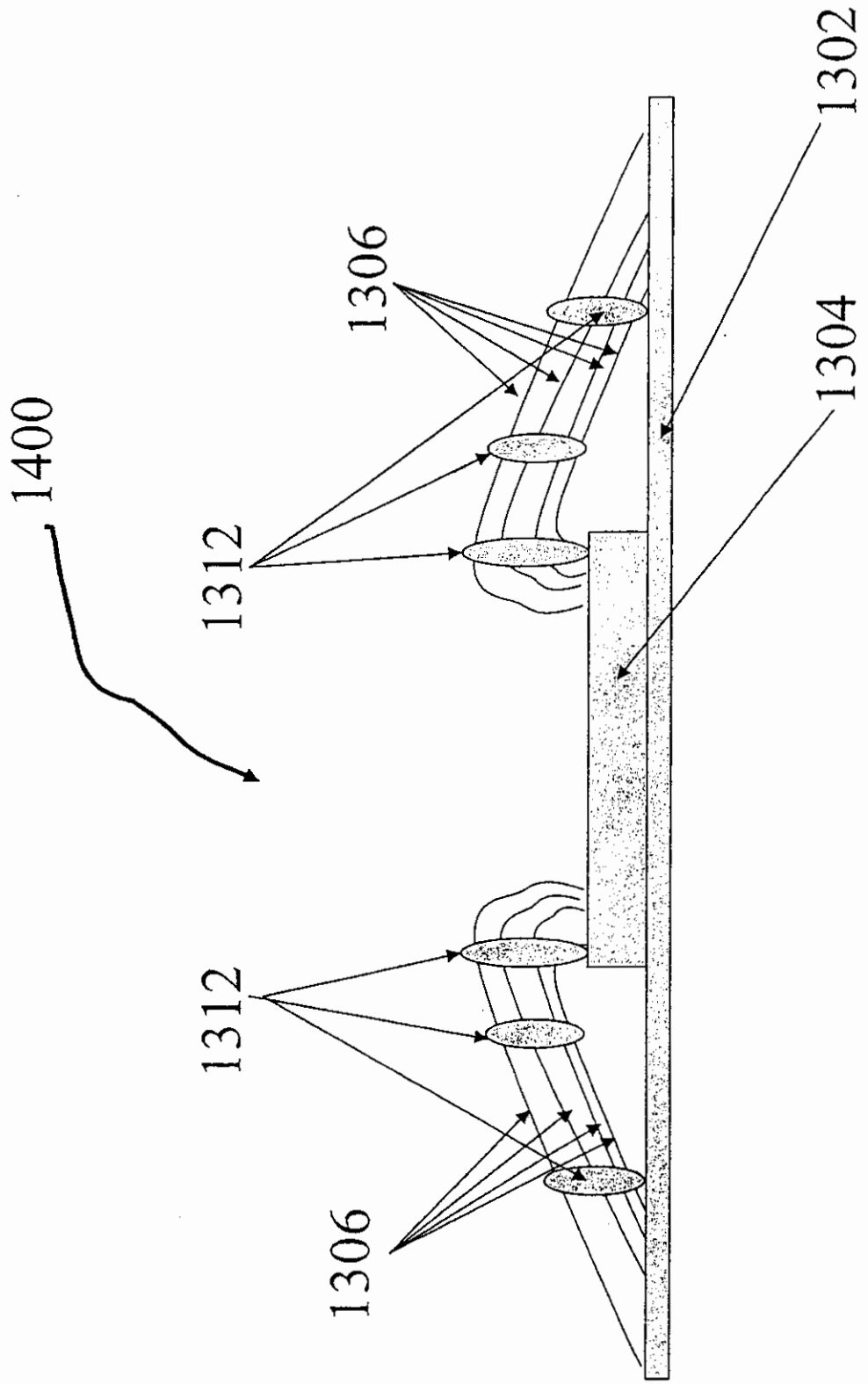


Fig.14A

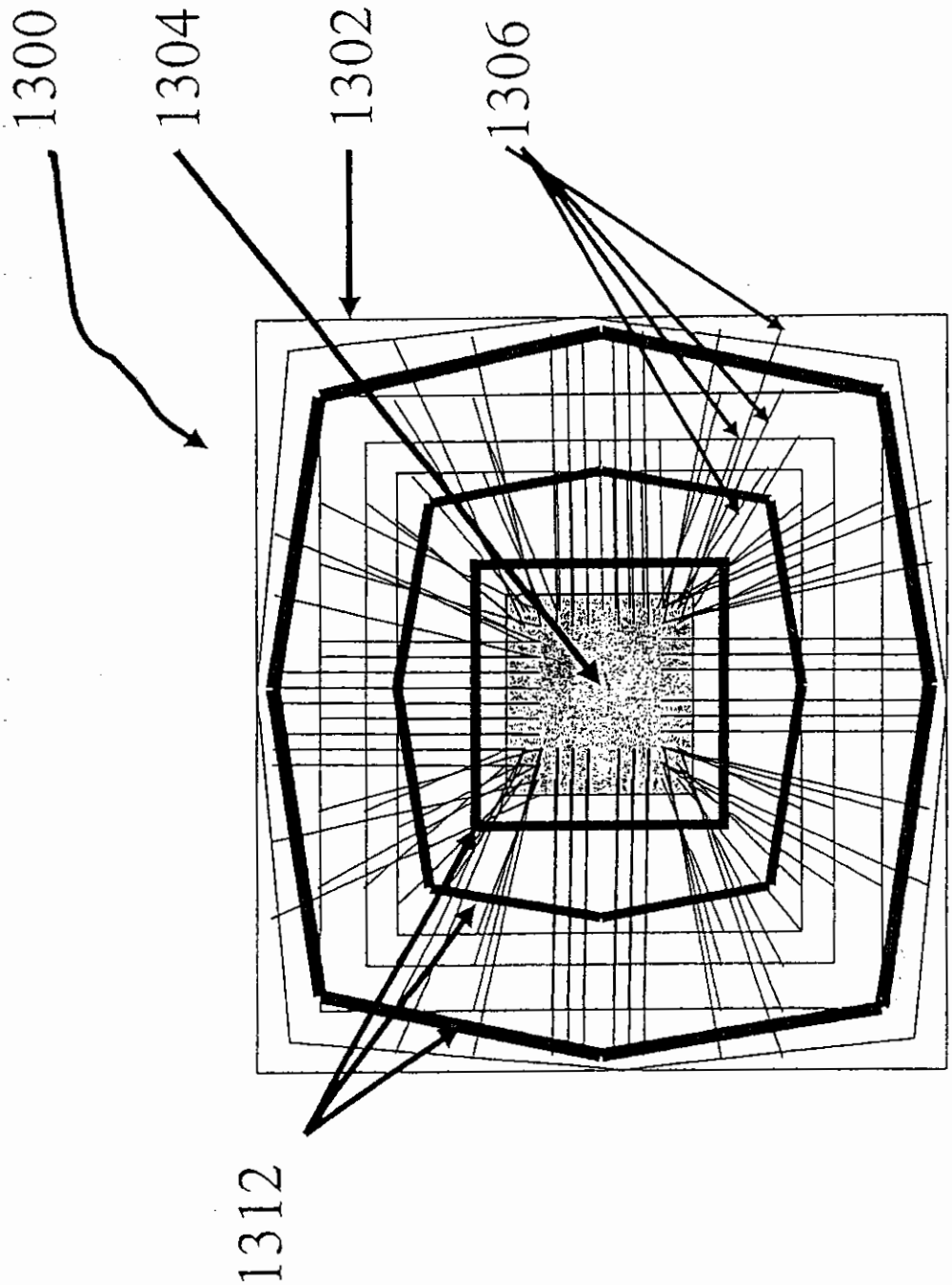


Fig.14B